

REMARKS

At the time of the Office Action dated December 14, 2004, claims 22-25 were pending in this application. Claim 24 has been rejected, and Applicants acknowledge, with appreciation, the Examiner's indication that claims 22-23 and 25 are allowable. Claim 24 has been amended and claims 27 and 28 have been added. Applicants submit that the present Amendment does not generate any new matter issue.

**CLAIM 24 IS REJECTED UNDER 35 U.S.C. § 102 FOR ANTICIPATION BASED UPON
FUJISAWA ET AL., U.S. PATENT NO. 5,801,439 (HEREINAFTER FUJISAWA)**

On page three of the Office Action, the Examiner asserted that Fujisawa identically discloses a composite semiconductor corresponding to that claimed. This rejection is respectfully traversed.

Initially, Applicants note that claim 24 has been amended to clarify that the claimed conductive member covers and is fixed to a side surface of a semiconductor chip. Referring to Fig. 12 of Applicants' disclosure, the conductive member (i.e., features 8, 8') covers and is fixed to a side surface of a semiconductor chip (i.e., features 7, 7'). Fixing the conductive member to the side surface of the semiconductor chip is effective in reinforcing a thin conductive member. As discussed on page 18 of Applicants' disclosure, through the use of this conductive member, semiconductor chips can be tightly stacked to produce a densely packaged semiconductor device. Since the number of electrodes on a semiconductor chip is increasing, which requires a reduction in the size of the electrodes, the conductive members connecting these electrodes are slender.

In the statement of the rejection, the Examiner referred specifically to Fig. 9B of Fujisawa and asserted that feature 21 corresponds to the claimed semiconductor chip and feature 24 corresponds to the claimed conductive member. In contrast to the claimed invention, the leads 24 of Fujisawa are shown in Fig. 9B as not being fixed to a side surface of the semiconductor chip 21. Instead, the leads 24 bridge over the side surface, and a gap exists between the leads 24 of Fujisawa and either a side surface of the semiconductor chip 21 or a plastic package 27 surrounding the semiconductor chip 21. To prevent deformation, the bridging structure of Fujisawa is thickened, which in contrast to the claimed invention, increases the profile of the semiconductor device. For the reasons stated above, Applicants respectfully solicit withdrawal of the imposed rejection of claim 24 under 35 U.S.C. § 102 for anticipation based upon Fujisawa.

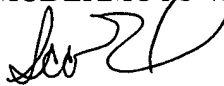
Dependent claims 27 and 28 depend from independent 24 and Applicants submit that a rejection of these claims under 35 U.S.C. § 102 for anticipation based upon Fujisawa would not be proper. Furthermore, claim 28 recites that the conductive member is directly fixed on a side surface of the semiconductor chip. In contrast, the leads 24 of Fujisawa are shown in Fig. 9B as not being directly fixed to either a side surface of the semiconductor chip 21 or a plastic package 27 disposed between the semiconductor chip 21 and the leads 24. Therefore, Fujisawa fails to identically disclose the claimed invention, as recited in claim 28. Thus, claim 28 further distinguishes the claimed invention over Fujisawa.

Applicants have made every effort to present claims which distinguish over the prior art, and it is believed that all claims are in condition for allowance. However, Applicants invite the Examiner to call the undersigned if it is believed that a telephonic interview would expedite the prosecution of the application to an allowance. Accordingly, and in view of the foregoing remarks, Applicants hereby respectfully request reconsideration and prompt allowance of the pending claims.

To the extent necessary, a petition for an extension of time under 37 C.F.R. § 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417, and please credit any excess fees to such deposit account.

Respectfully submitted,

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